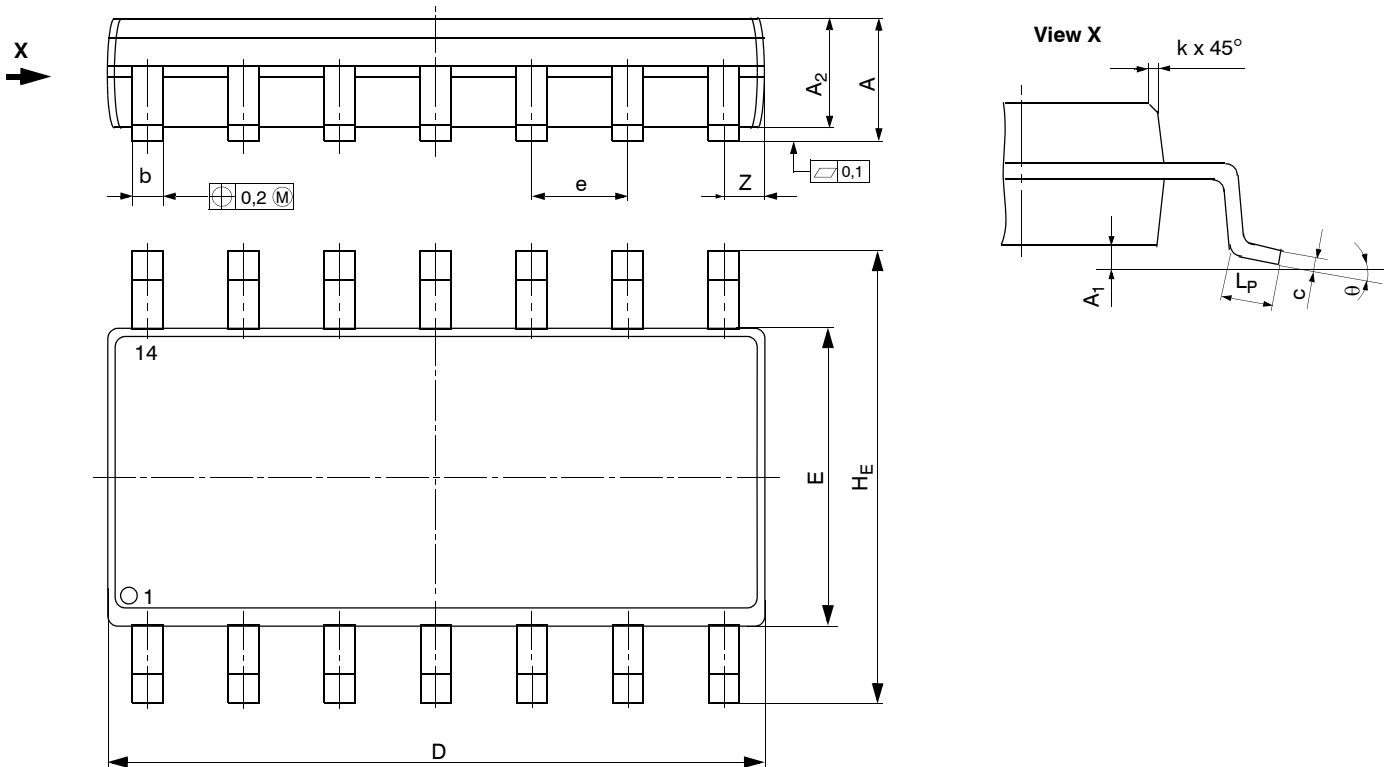
	Package SOP14 (150 mil)	MDS 748
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Dimensions in millimetres

Based on IEC 191-2Q: Type 076E06S

1 Dimensions

Dimensions of Sub-Group B1	
A_{\max}	1,73
$b_{P\min}$	0,35
$b_{P\max}$	0,49
e_{nom}	1,27
$H_{E\min}$	5,80
$H_{E\max}$	6,30
$L_{P\min}$	0,40
Z_{\max}	0,56

Dimensions of Sub-Group C1	
A_{\min}	1,55
$A_{1\min}$	0,127
$A_{1\max}$	0,25
$A_{2\min}$	1,40
$A_{2\max}$	1,55
c_{\min}	0,19
c_{\max}	0,25
D_{\min}^*	8,58
D_{\max}^*	8,74
E_{\min}^*	3,80
E_{\max}^*	4,00
k_{\min}	0,25
θ_{\min}	0°
θ_{\max}	8°

- 2 Weight** $\leq 0,5$ g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

* without mold-flash

Zentrum Mikroelektronik Dresden AG		
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